Power MOSFET

40 V, 167 A, Single N-Channel, D²PAK & TO-220

Features

- Low R_{DS(on)}
- High Current Capability
- Low Gate Charge
- AEC-Q101 Qualified and PPAP Capable NVB5404N
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Electronic Brake Systems
- Electronic Power Steering
- Bridge Circuits

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter			Symbol	Value	Units
Drain-to-Source Voltage			V _{DSS}	40	V
Gate-to-Source Voltage	е		V_{GS}	±20	V
Continuous Drain	Steady	T _C = 25°C	I _D	167	Α
Current – R _{θJC}	State	T _C = 100°C		118	
Power Dissipation – $R_{\theta JC}$	Steady State	T _C = 25°C	P _D	254	W
Continuous Drain	Steady State	T _A = 25°C	I _D	24	Α
Current – R _{θJA} (Note 1)	State	T _A = 100°C	1	17	
Power Dissipation – R _{θJA} (Note 1)	Steady State	T _A = 25°C	P _D	5.4	W
Pulsed Drain Current	t _p :	= 10 μs	I _{DM}	670	Α
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 175	°C
Source Current (Body Diode) Pulsed			I _S	75	Α
Single Pulse Drain–to Source Avalanche Energy – (V_{DD} = 50 V, V_{GS} = 10 V, I_{PK} = 45 A, L = 1 mH, R_G = 25 Ω)			EAS	1000	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	0.59	°C/W
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	50	°C/W

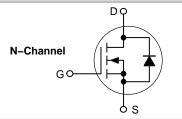
Surface mounted on FR4 board using 1 sq in pad size, (Cu Area 1.127 sq in [2 oz] including traces).

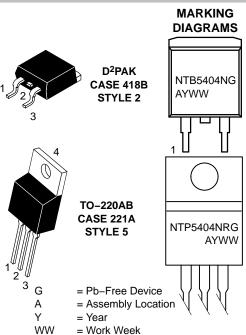


ON Semiconductor®

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V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX (Note 1)
40 V	4.5 mΩ @ 10 V	167 A





ORDERING INFORMATION

ONDERING INI ONWATION					
Device	Package	Shipping†			
NTB5404NT4G	D ² PAK (Pb-Free)	800 / Tape & Reel			
NTP5404NRG	TO-220 (Pb-Free)	50 Units / Rail			
NVB5404NT4G	D ² PAK (Pb-Free)	800 / Tape & Reel			

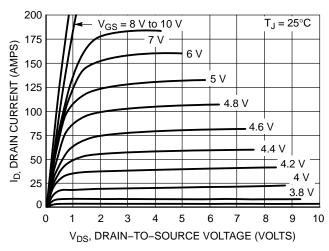
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				34		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V,	T _J = 25°C			1.0	μΑ
		$V_{DS} = 40 \text{ V}$	T _J = 100°C			10	
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{G}$	_S = ±30 V			±100	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_{D}$	= 250 μΑ	1.5		3.5	V
Gate Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-8.2		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I	_D = 40 A		3.5	4.5	mΩ
		$V_{GS} = 5.0 \text{ V},$	I _D = 15 A		5.1	7.0	7
Forward Transconductance	9FS	V _{DS} = 10 V, I	_D = 15 A		35		S
CHARGES AND CAPACITANCES	•				•	•	
Input Capacitance	C _{ISS}				4300	7000	pF
Output Capacitance	C _{OSS}	$V_{GS} = 0 \text{ V, f} = V_{DS} = 3$	1.0 MHz,		1075	1700	
Reverse Transfer Capacitance	C _{RSS}	VDS = 0	⁻ '		450	1000	
Total Gate Charge	Q _{G(TOT)}				125		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V. V _I	ns = 32 V.		5.5		
Gate-to-Source Charge	Q_{GS}	$V_{GS} = 10 \text{ V}, V_{I}$ $I_{D} = 40$	ÎĂ ,		12.5		
Gate-to-Drain Charge	Q_{GD}	†			55		
SWITCHING CHARACTERISTICS, Vo	_{SS} = 10 V (Note	3)	•			•	•
Turn-On Delay Time	t _{d(ON)}				10		ns
Rise Time	t _r	V _{GS} = 10 V. V _I	nn = 32 V.		65		
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = 10 \text{ V}, V_{I}$ $I_{D} = 40 \text{ A}, R_{C}$	$_{\rm G} = 2.5 \Omega$		85		
Fall Time	t _f				85		
SWITCHING CHARACTERISTICS, Vo	_{iS} = 5 V (Note 3)	•			•	•
Turn-On Delay Time	t _{d(ON)}				25		ns
Rise Time	t _r	$V_{GS} = 5 \text{ V}, V_{D}$	n = 20 V.		175		
Turn-Off Delay Time	t _{d(OFF)}	$I_D = 20 \text{ A}, R_C$	$_{\rm G} = 2.5 \Omega$		46		
Fall Time	t _f				62		1
DRAIN-SOURCE DIODE CHARACTE	RISTICS		•				
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	T _J = 25°C		0.8	1.1	V
		$V_{GS} = 0 V,$ $I_{S} = 20 A$	T _J = 125°C		0.65		7
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_{SD}/dt = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 20 \text{ A}$			75		ns
Charge Time	ta				38		
Discharge Time	t _b				38		7
Reverse Recovery Charge	Q _{RR}				140		nC

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

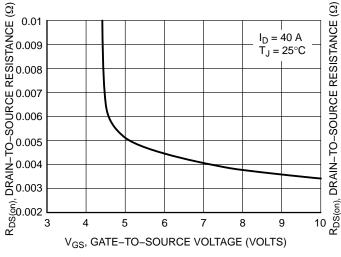
TYPICAL PERFORMANCE CURVES



200 $V_{DS} \ge 10 \text{ V}$ 175 ID, DRAIN CURRENT (AMPS) 150 125 100 75 $T_{.1} = 25^{\circ}C$ 50 25 125°C $T_J = -55^{\circ}C$ 0 2 10 0 6 8 9 3 4 V_{GS}, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



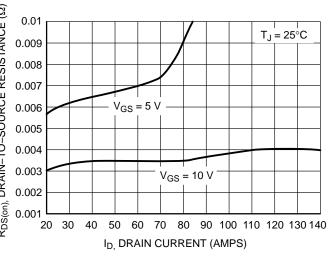
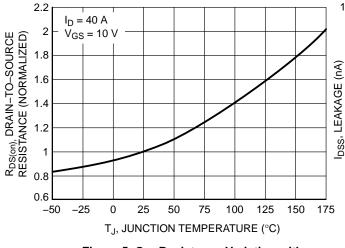


Figure 3. On-Resistance vs. Gate-to-Source Voltage

Figure 4. On-Resistance vs. Drain Current and Gate Voltage



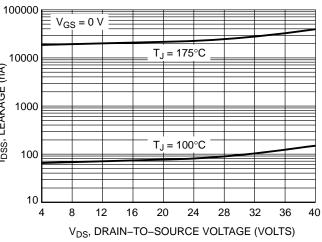
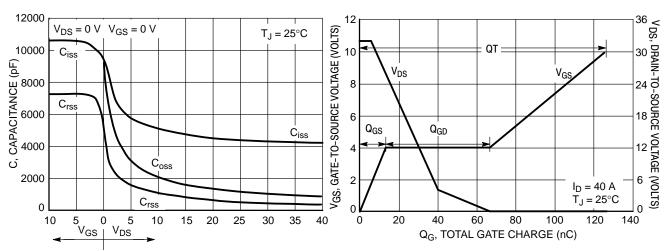


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL PERFORMANCE CURVES



GATE-TO-SOURCE OR DRAIN-TO-SOURCE VOLTAGE (VOLTS)

Figure 7. Capacitance Variation

Figure 8. Gate-To-Source and Drain-To-Source Voltage vs. Total Charge

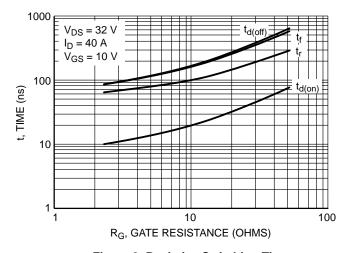


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

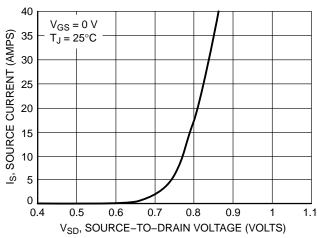


Figure 10. Diode Forward Voltage vs. Current

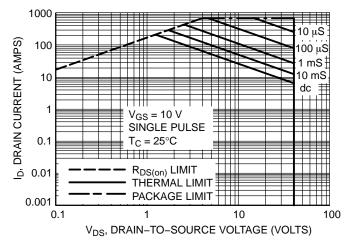


Figure 11. Maximum Rated Forward Biased Safe Operating Area

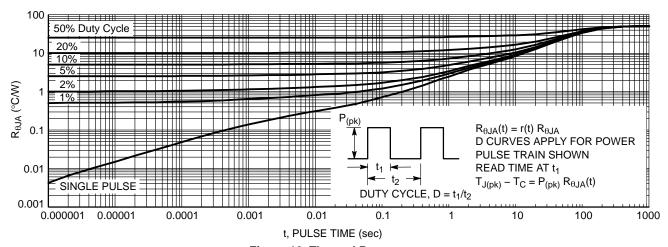
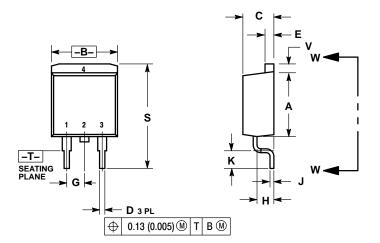


Figure 12. Thermal Response

PACKAGE DIMENSIONS

D²PAK CASE 418B-04 **ISSUE K**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE,

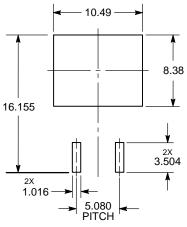
 - NEW STANDARD 418B-04.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54	BSC
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197	REF	5.00	REF
Р	0.079	REF	2.00	REF
R	0.039	REF	0.99	REF
S	0.575	0.625	14.60	15.88
٧	0.045	0.055	1.14	1.40

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE

- 4. DRAIN

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



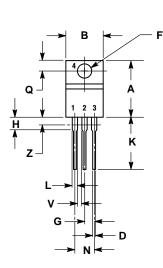
VIEW W-W

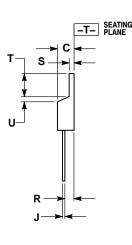
VARIABLE CONFIGURATION ZONE

М

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- CONTROLLING DIMENSION: INCH.
 DIMENSION Z DEFINES A ZONE WHERE ALL
 BODY AND LEAD IRREGULARITIES ARE ALLOWED

	INCHES		MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.415	9.66	10.53	
С	0.160	0.190	4.07	4.83	
D	0.025	0.038	0.64	0.96	
F	0.142	0.161	3.61	4.09	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.161	2.80	4.10	
J	0.014	0.024	0.36	0.61	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Z		0.080		2.04	

STYLE 5: PIN 1.

DRAIN

- SOURCE 3.

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